IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1					Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfc Information			
upplier Informa	ation													
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
nsemi											2025-07-31			
Contact Name			Title - Contact			P	Phone - Contact*				Email - Contact*			
Product-Env-Stewar	rds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
uthorized Represen	ntative*		Title - Representative			P	Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester	Requester Item Number		Mfr Item Number Mfr Item Name			Effectiv		Version	M	lanufacturing Site	Wei	ight*	UOM	Unit Type
		NDS352AP 30V S		30V SSOT-3 PCH	30V SSOT-3 PCH		2025-07-31		М	MY1		57	mg	Each
	Process Informatio		arminal Raca	Alloy	STD-020 MSL F	Pating	Dank Droop	es Rody Ta	mnarature	Max Time at Peak	Tamparatura	Numbe	er of Reflow Cyc	Jac
			Terminal Base Alloy J-STE CU Alloy 1		31D-020 MSL F	Nating	260			30	seconds	3	el of Kellow Cyc	ies
•	(Sii) - aimealeu	C	U Anoy	1			200		<u> </u>	30	seconds	13		
omments	me at peak temperature	during cal	doring is 10.3	0 seconds										
r more information	n regarding material co	mposition p	olease refer to	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.766	mg	Supplier	Silicon (Si)	7440-21-3		0.766	mg
Lead Frame	3.699	mg	Supplier	Silver (Ag)	7440-22-4		0.015	mg
			Supplier	Zinc (Zn)	7440-66-6		0.005	mg
			Supplier	Iron (Fe)	7439-89-6		0.088	mg
			Supplier	Copper (Cu)	7440-50-8		3.59	mg
			Supplier	Phosphorus (P)	7723-14-0		0.001	mg
Mold Compound-Black	5.697		Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.65	mg
			Supplier	Carbon Black (C)	1333-86-4		0.057	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.99	mg
Plating	0.332	mg	Supplier	Tin (Sn)	7440-31-5		0.332	mg
Wire Bond - Au	0.076	mg	Supplier	Gold (Au)	7440-57-5		0.076	mg